

QM3001K

P-Ch 30V Fast Switching MOSFETs



General Description

The QM3001K is the highest performance trench P-ch MOSFETs with extreme high cell density, which provide excellent R_{DS(on)} and gate charge for most of the small power switching and load switch applications.

The QM3001K meet the RoHS and Green Product requirement, with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Green Device Available

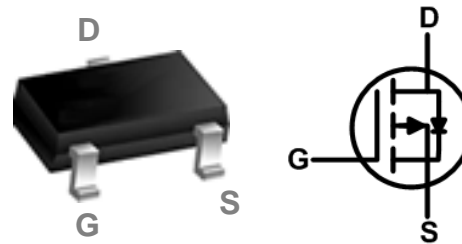
Product Summary

BVDSS	R _{DS(on)}	I _D
-30V	52mΩ	-3.3A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

TO252 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		10s	Steady State	
V _{DS}	Drain-Source Voltage	-30		V
V _{GS}	Gate-Source Voltage	±20		V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-3.8	-3.3	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ -10V ¹	-3.1	-2.7	A
I _{DM}	Pulsed Drain Current ²	-17		A
P _D @T _A =25°C	Total Power Dissipation ³	1.32	1	W
P _D @T _A =70°C	Total Power Dissipation ³	0.84	0.64	W
T _{STG}	Storage Temperature Range	-55 to 150		°C
T _J	Operating Junction Temperature Range	-55 to 150		°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	125	°C/W
R _{θJA}	Thermal Resistance Junction-Ambient ¹ (t ≤ 10s)	---	95	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	80	°C/W

QM3001K

P-Ch 30V Fast Switching MOSFETs

Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-30	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=-1\text{mA}$	---	-0.023	---	V/ $^\circ\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=-10V, I_D=-3A$	---	42	52	m Ω
		$V_{GS}=-4.5V, I_D=-2A$	---	75	90	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	-1.2	-1.6	-2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	4	---	mV/ $^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-24V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	-1	μA
		$V_{DS}=-24V, V_{GS}=0V, T_J=55^\circ\text{C}$	---	---	-5	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=-5V, I_D=-3A$	---	11	---	S
Q_g	Total Gate Charge (-4.5V)	$V_{DS}=-15V, V_{GS}=-4.5V, I_D=-3A$	---	6.4	9.0	nC
Q_{gs}	Gate-Source Charge		---	2.3	3.2	
Q_{gd}	Gate-Drain Charge		---	1.9	2.7	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=-15V, V_{GS}=-10V, R_G=3.3\Omega, I_D=-3A$	---	2.8	5.6	ns
T_r	Rise Time		---	8.4	15.1	
$T_{d(off)}$	Turn-Off Delay Time		---	39	78.0	
T_f	Fall Time		---	6	12.0	
C_{iss}	Input Capacitance	$V_{DS}=-15V, V_{GS}=0V, f=1\text{MHz}$	---	583	816	pF
C_{oss}	Output Capacitance		---	100	140	
C_{rss}	Reverse Transfer Capacitance		---	80	112	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current ^{1,4}	$V_G=V_D=0V$, Force Current	---	---	-3.3	A
I_{SM}	Pulsed Source Current ^{2,4}		---	---	-17	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V, I_S=-1A, T_J=25^\circ\text{C}$	---	---	-1	V
t_{rr}	Reverse Recovery Time	$I_F=-3A, dI/dt=100A/\mu s, T_J=25^\circ\text{C}$	---	7.8	---	nS
Q_{rr}	Reverse Recovery Charge		---	2.5	---	nC

Note :

- The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- The power dissipation is limited by 150°C junction temperature
- The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.